| © Co   | erial Composition<br>pyright 2005. IPC, Ba<br>national and Pan-Ame                                   | nnockburn, Illi  | inois. All rights reserved            | under both  | This docume<br>level parts, th | ent is a declara<br>he declaration                              | ation of the s | substances<br>es all lower | within the m<br>level mater | nanufacture<br>rials for wh     | er listed iter<br>iich the mar  | n. Note: i<br>nufacturer          | f the item is an as<br>has engineering | sembly with lower responsibility. |  |
|--|--|------------------|---------------------------------------|---|--------------------------------|---|----------------|----------------------------|-----------------------------|---------------------------------|---------------------------------|-----------------------------------|--|-----------------------------------|--|
|  | IPC Web Site for Information on IPC-1752 Standard Form Typ<br>http://www.ipc.org/IPC-175x Distribute |                  |                                       |   | *                              | Declaration Class *<br>Class 6 - RoHS Yes/No, Homogeneous Mater |                |                            |                             |                                 | ials and Mfg Information        |                                   |  |                                   |  |
| Supplier Information                           |  |                  |                                       |   |                                |   |                |                            |                             |                                 |                                 |                                   |  |                                   |  |
| Company name*                                  |  |                  | Company unique ID                     |   |                                | Unique ID Authority   |                |                            |                             |                                 | Response Date*                  |                                   |  |                                   |  |
| onsemi   |  |                  |                                       |   |                                |   |                |                            |                             |                                 | 2025-06-08                      |                                   |  |                                   |  |
| Contact Name                                   |  |                  | Title - Contact                       |   |                                | Phone - Contact*  |                |                            |                             |                                 | Email - Contact*                |                                   |  |                                   |  |
| Product-Env-Stewards                           |  |                  | Product Enviro Compliance             |   |                                | NA  |                |                            |                             |                                 | Product-Env-Stewards@onsemi.com |                                   |  |                                   |  |
| Authorized Representative*                     |  |                  | Title - Representative                |   |                                | Phone - Representative*   |                |                            |                             | Email - Representative*         |                                 |                                   |  |                                   |  |
| Product-Env-Stewards                           |  |                  | Product Enviro Compliance             |   |                                | NA  |                |                            |                             | Product-Env-Stewards@onsemi.com |                                 |                                   |  |                                   |  |
| Requester Item N                               | Requester Item Number Mfr Iter   |                  | n Number Mfr Item Name                |   |                                | Effective Date Version Manufacturing Sit                        |                | ng Site                    | W                           | eight*                          | UOM                             | Unit Type                         |  |                                   |  |
|  | NCV8170BMX250TC<br>G   |                  | 250TC 150mA LDO, U<br>State, Vout=2.5 | 150mA LDO, Ultra Low Iq, High Ohmic<br>State, Vout=2.5V, automotive |                                | 2025-06-08  |                | N                          | MY1                         |                                 | 1.4                             | -34                               | mg                                     | Each                              |  |
| Manufacturing Procee                           | ess Information  |                  |                                       |   |                                |   |                |                            |                             |                                 |                                 |                                   |  |                                   |  |
| Terminal Plating                               | minal Plating / Grid Array Material Tern   |                  | l Base Alloy                          | e Alloy J-STD-020 MSL Ratin   |                                | Peak Process Body Tempera                                       |                | Femperatur                 | ure Max Time at Peak Tempe  |                                 | Гетрегаtur                      | nperature Number of Reflow Cycles |  | les                               |  |
| Precious metal (e.g. Ag,Au, NiPdAu) (no<br>Sn) |  | (no CU Allog     | CU Alloy 1                            |   |                                | 260   |                | С                          |                             | 30 seco                         |                                 | seconds 3                         |  |                                   |  |
| Comments                                       |  |                  |                                       |   |                                |   |                |                            |                             |                                 |                                 |                                   |  |                                   |  |
| evel 1 - maximum time at p                     | eak temperature du   | ring soldering   | is 10-30 seconds                      |   |                                |   |                |                            |                             |                                 |                                 |                                   |  |                                   |  |
| For more information rega                      | rding material compo   | osition please r | refer to page 3                       |   |                                |   |                |                            |                             |                                 |                                 |                                   |  |                                   |  |

| RoHS Material Composition Declaration  |   |  |   | Declaration Type *                              | Detailed  |  |  |  |  |  |  |  |
|--|---|--|---|---|---|--|--|--|--|--|--|--|
| Directive 2015/863/EU amending RoHS<br>Directive 2011/65/EU  | RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP). |  |   |   |   |  |  |  |  |  |  |  |
| cadmium, hexavalentchromium, polybrominate<br>contains a RoHS restricted substance inexcess<br>encompass all such components. Supplier certif<br>as of the date that Supplier completes this form<br>Company acknowledges that Supplier may hav<br>independently verified information provided by<br>certification in this paragraph. If the Company a | ed biphenyls and/or polybrominated dip<br>of an applicable quantity limit, please ir<br>ies that it gathered the information it pro-<br>.Supplier acknowledges that Company<br>e relied on informationprovided by othe<br>v others, Supplier agrees that, at a minin<br>and the Supplier enter into a written agre<br>pource of the Supplier's liability and the  | henyl ethers (each a "<br>ndicate below which, i<br>ovides in this form us<br>will rely on this certifiers<br>in completing this<br>num, itssuppliers have<br>eement with respect to<br>Company's remedies | RoHS restricted substance") in exce<br>if any, RoHS exemption you believe<br>ing appropriate methods to ensure if<br>ication in determining the complian<br>form, and that Supplier may not have<br>e provided certifications regarding the<br>to the identified part, the terms and co<br>for issues that arise regarding inform | ce of its products with European Union membe    | ove. If a homogeneous material within the part<br>er level components, the declaration shall<br>l correct to the best of its knowledge and belief,<br>r state laws that implement the RoHS Directive.<br>wever, in situations where Supplier has not<br>tions are at least as comprehensive as the<br>anty rights and/or remedies provided as part of |  |  |  |  |  |  |  |
| RoHS Declaration * 1 - Item(s)   | does not contain RoHS restricted substa   | ances per the definitio  | on above  | Supplier Acceptance                             | * Accepted  |  |  |  |  |  |  |  |
| Exemption: If the declared item does not con applicable exemptions.  | ntain RoHS restricted substances per  | the definition above   | except for defined RoHS exempti   | ons, then select the corresponding response i   | n the RoHS Declaration above and choose all   |  |  |  |  |  |  |  |
| Exemption List Version   | EL-2011/534/EU  |  |   |   |   |  |  |  |  |  |  |  |
| Declaration Signature  |   |  |   |   |   |  |  |  |  |  |  |  |
| Instructions: Complete all of the required fin<br>Requester) and click on Submit Form to have  | elds on all pages of this form. Select the form returned to the Requester   | he "Accepted" on th  | e Supplier Acceptance drop-down   | . This will display the signature area. Digital | lly sign the declaration (if required by the  |  |  |  |  |  |  |  |
| Supplier Digital Signature Ra  | stislav Drska   | Le   |   |   |   |  |  |  |  |  |  |  |

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

| Homogeneous Material | Weight | Unit of Measure | Level    | Substance  | CAS         | Exempt | Weight | Unit of Measure |
|----------------------|--------|-----------------|----------|--|-------------|--------|--------|-----------------|
| Die                  | 0.09   | mg              | Supplier | Silicon (Si)   | 7440-21-3   |        | 0.09   | mg              |
| Die Attach           | 0.13   | mg              | Supplier | Epoxized Condensate Of Para-<br>Hydrobenzaldehyde And Alkyl Phenol | 129915-35-1 |        | 0.0416 | mg              |
|                      |        |                 | Supplier | Aluminum Trioxide (Al2O3)  | 1344-28-1   |        | 0.0884 | mg              |
| Lead Frame           | 0.58   | mg              | Supplier | Tin (Sn)   | 7440-31-5   |        | 0.0014 | mg              |
|                      |        |                 | Supplier | Zinc (Zn)  | 7440-66-6   |        | 0.0013 | mg              |
|                      |        |                 | Supplier | Chromium (Cr)  | 7440-47-3   |        | 0.0014 | mg              |
|                      |        |                 | Supplier | Copper (Cu)  | 7440-50-8   |        | 0.5758 | mg              |
| Mold Compound-Black  | 0.6    | mg              | Supplier | Epoxy and Phenolic Resin   | 40216-08-8  |        | 0.048  | mg              |
|                      |        | -               | Supplier | Carbon Black (C)   | 1333-86-4   |        | 0.003  | mg              |
|                      |        |                 | Supplier | Aluminum Hydroxide (Al(OH)3)                                       | 21645-51-2  |        | 0.012  | mg              |
|                      |        |                 | Supplier | Fused Silica (SiO2)  | 60676-86-0  |        | 0.519  | mg              |
|                      |        |                 | Supplier | Phenolic Resin (Novolac)   | 9003-35-4   |        | 0.018  | mg              |
| Plating              | 0.004  | mg              | Supplier | Palladium (Pd)   | 7440-05-3   |        | 0.0001 | mg              |
|                      |        |                 | В        | Nickel (Ni)  | 7440-02-0   |        | 0.0035 | mg              |
|                      |        |                 | Supplier | Gold (Au)  | 7440-57-5   |        | 0.0004 | mg              |
| Wire Bond - Au       | 0.03   | mg              | Supplier | Gold (Au)  | 7440-57-5   |        | 0.03   | mg              |

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).